

MUR550APFG, MURD550PFG, MUR550PFG, MURF550PFG, NRVUD550PFT4G



ON Semiconductor®

<http://onsemi.com>

SWITCHMODE Power Rectifier

These state-of-the-art devices are designed for power factor correction in discontinuous and critical conduction mode.

Features

- 520 V Rating Meets 80% Derating Requirements of Major OEMs
- Low Forward Voltage Drop
- Low Leakage
- Ultrafast 95 Nanosecond Recovery Time
- Reduces Forward Conduction Loss
- AEC-Q101 Qualified and PPAP Capable
- NRVUD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb-Free*

Applications

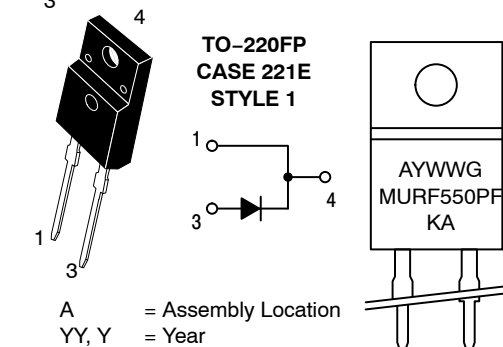
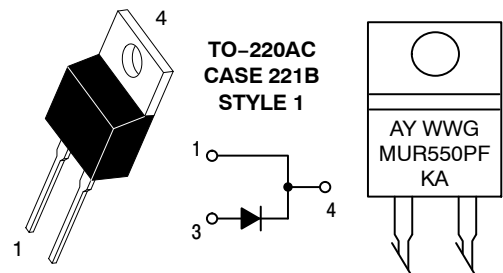
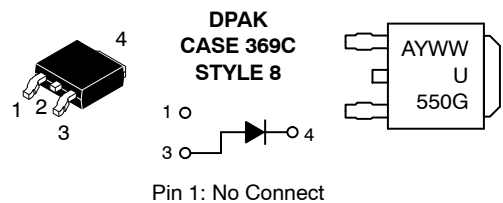
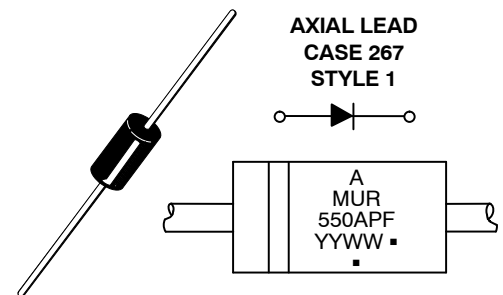
- DCM PFC Designs
- Switching Power Supplies
- Power Inverters

Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: MUR550APFG: 1.1 Gram (Approximately)
MURD550PFG, NRVUD550PFT4G: 0.4 Gram (Approximately)
MUR550PFG, MURF550PFG: 1.9 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

ULTRAFast RECTIFIER 5.0 AMPERES, 520 VOLTS

MARKING DIAGRAMS



A = Assembly Location
YY, Y = Year
WW = Work Week
▪ or G = Pb-Free Package
KA = Diode Polarity

(Note: Microdot may be in either location)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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ORDERING INFORMATION

Device	Package	Shipping†
MUR550APFG	Axial	500 Units/Bag
MUR550APFRLG	Axial	1,500 Tape & Reel
MURD550PFT4G	DPAK (Pb-Free)	2,500 Tape & Reel
NRVUD550PFT4G	DPAK (Pb-Free)	2,500 Tape & Reel
MUR550PFG	TO-220AC (Pb-Free)	50 Units/Rail
MURF550PFG	TO-220FP (Pb-Free)	50 Units / Rail

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	520	V
Average Rectified Forward Current (Rated V_R) $T_C = 65^\circ\text{C}$ (Rated V_R) $T_C = 160^\circ\text{C}$	$I_{F(AV)}$	5.0 5.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, 60 Hz)	I_{FSM}	85 75 100	A
Operating Junction Temperature Range	T_J	-65 to +175	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +175	$^\circ\text{C}$
ESD Ratings: Machine Model = C Human Body Model = 3B	ESD	> 400 > 8000	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Note 1) MURD550PG, MUR550PFG, NRVUD550PFT4G MURF550PFG	$R_{\theta JC}$	2.8 5.75	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient MUR550APFG NRVUD550PFT4G, MURD550PFG (Note 3), MURF550PFG	$R_{\theta JA}$	Note 2 62 75	$^\circ\text{C}/\text{W}$

1. Rating applies when surface mounted on the minimum pad sizes recommended.
2. See Note 2, Ambient Mounting Data.
3. 1 inch square pad size on FR4 board.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage Drop (Note 4) ($I_F = 5.0\text{ A}$, $T_J = 25^\circ\text{C}$) ($I_F = 5.0\text{ A}$, $T_J = 150^\circ\text{C}$)	V_F	1.15 0.98	V
Maximum Instantaneous Reverse Current (Note 4) ($V_R = 520\text{ V}$, $T_J = 25^\circ\text{C}$) ($V_R = 520\text{ V}$, $T_J = 150^\circ\text{C}$)	I_R	5.0 400	μA
Maximum Reverse Recovery Time ($I_F = 1.0\text{ A}$, $di/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $T_J = 25^\circ\text{C}$)	t_{rr}	95	ns

4. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

NOTE 2 — AMBIENT MOUNTING DATA

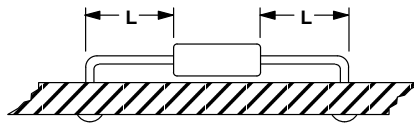
Data shown for thermal resistance junction-to-ambient ($R_{\theta JA}$) for the mountings shown is to be used as typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

TYPICAL VALUES FOR $R_{\theta JA}$ IN STILL AIR

Mounting Method	$R_{\theta JA}$	Lead Length, L (IN)				Units
		1/8	1/4	1/2	3/4	
1		50	51	53	55	°C/W
2		58	59	61	63	°C/W
3		28				°C/W

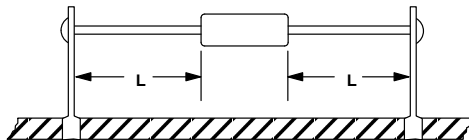
MOUNTING METHOD 1

P.C. Board Where Available Copper Surface area is small.



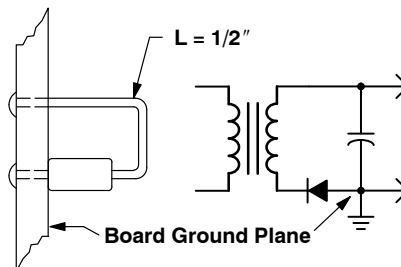
MOUNTING METHOD 2

Vector Push-In Terminals T-28



MOUNTING METHOD 3

P.C. Board with 1-1/2" x 1-1/2" Copper Surface



MUR550APFG, MURD550PFG, MUR550PFG, MURF550PFG, NRVUD550PFT4G

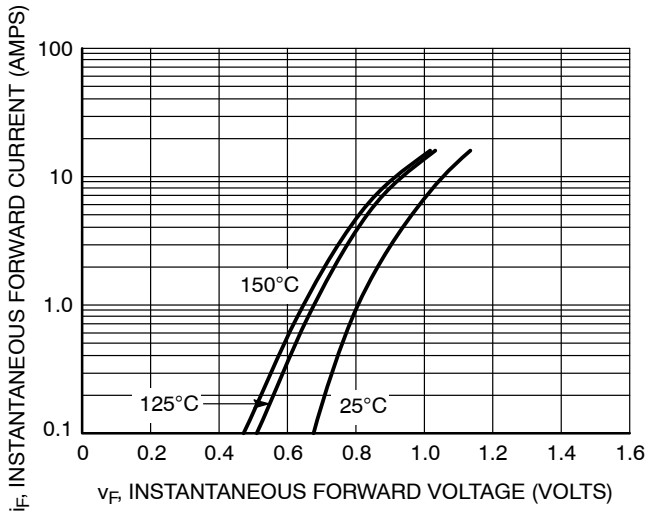


Figure 1. Typical Forward Voltage

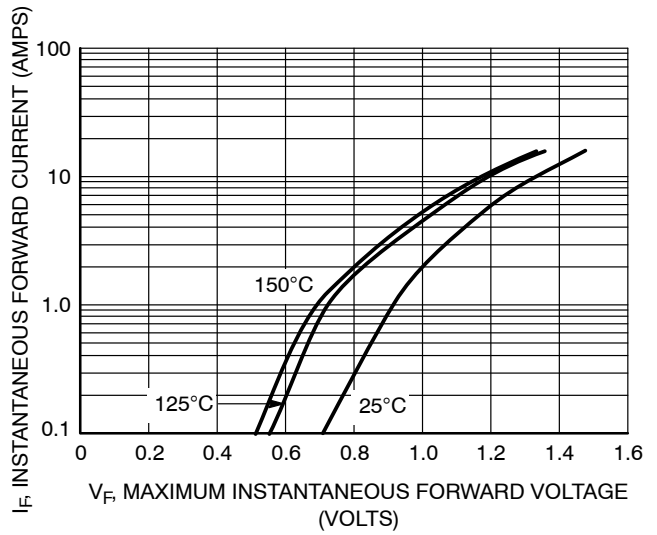


Figure 2. Maximum Forward Voltage

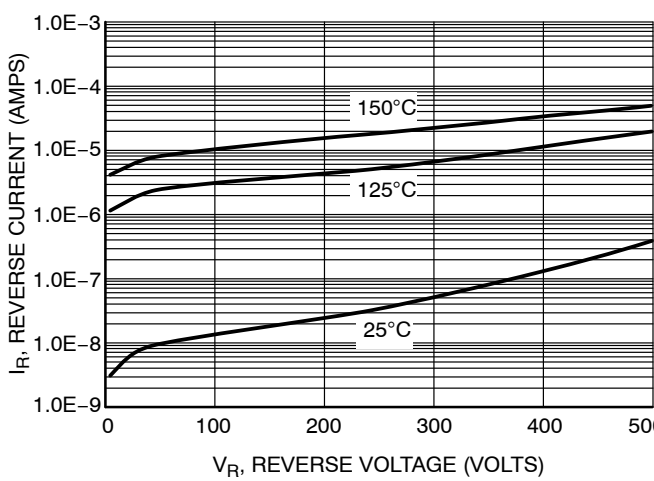


Figure 3. Typical Reverse Current

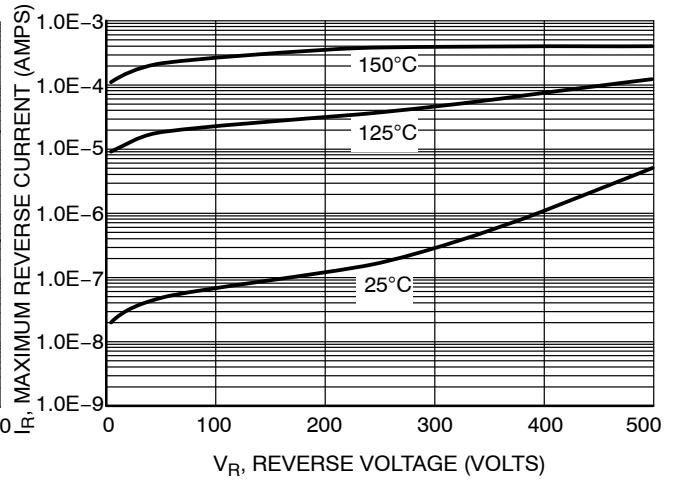


Figure 4. Maximum Reverse Current

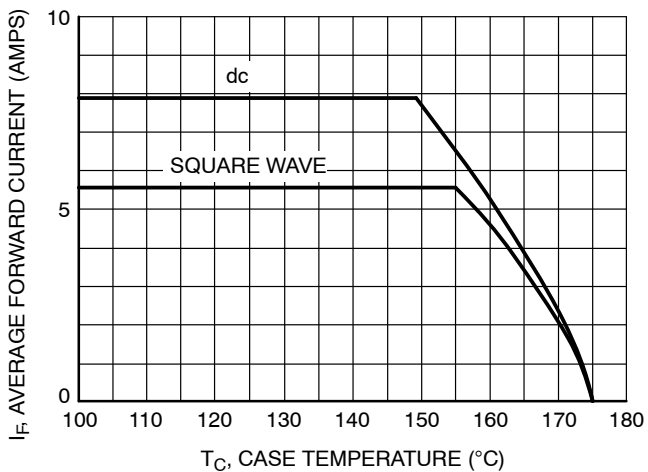


Figure 5. Current Derating

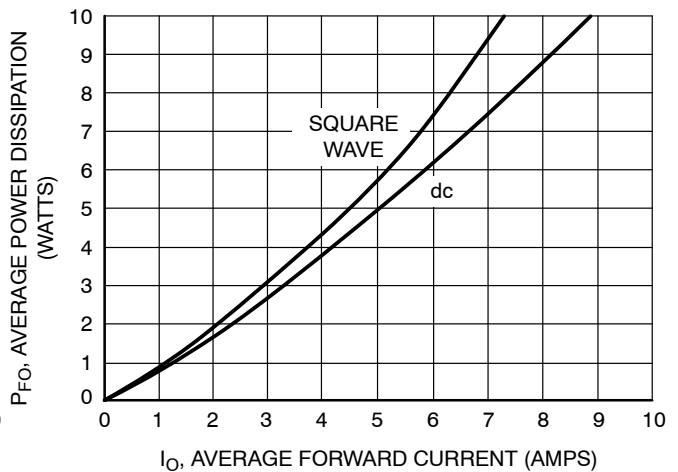


Figure 6. Forward Power Dissipation

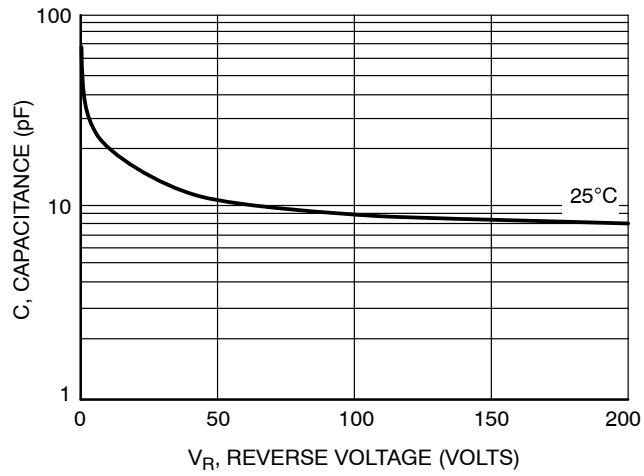


Figure 7. Capacitance

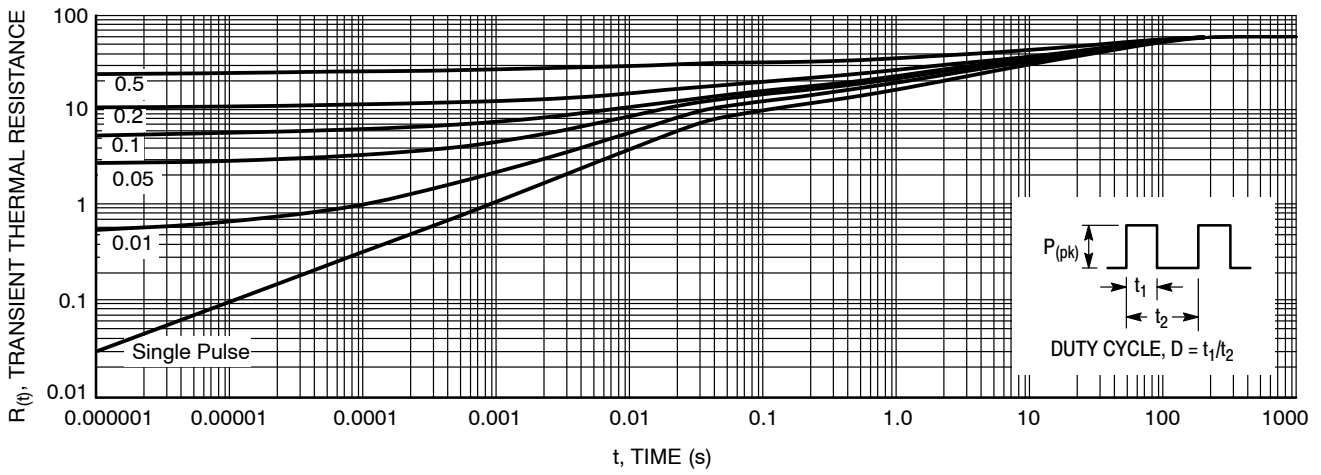


Figure 8. Thermal Response for MUR550APFG

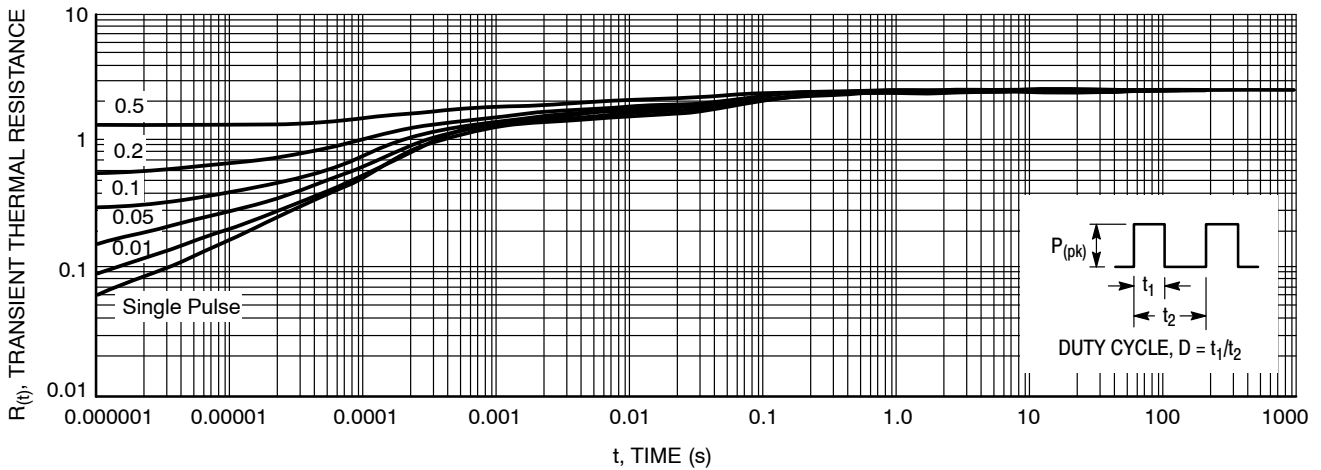


Figure 9. Thermal Response for MURD550PFG, NRVUD550PFT4G

MUR550APFG, MURD550PFG, MUR550PFG, MURF550PFG, NRVUD550PFT4G

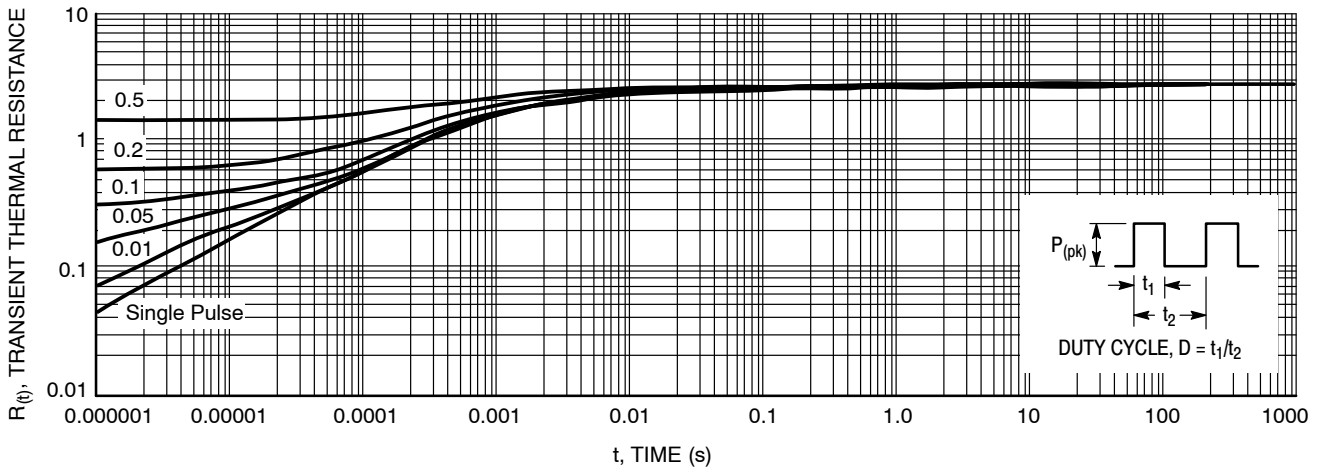


Figure 10. Thermal Response for MUR550PFG

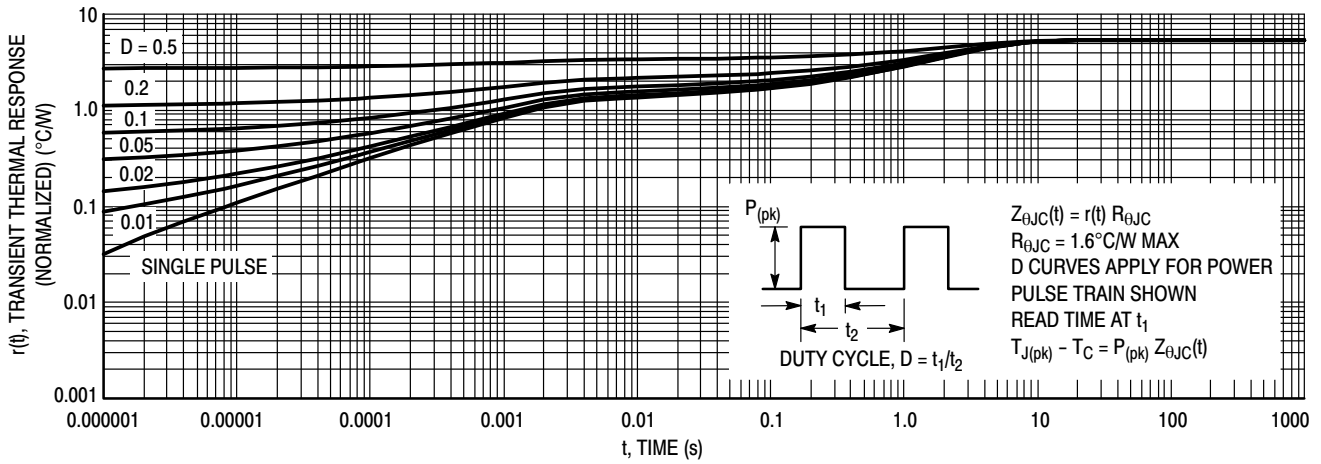


Figure 11. Thermal Response, (MURF550PFG) Junction-to-Case ($R_{\theta JC}$)

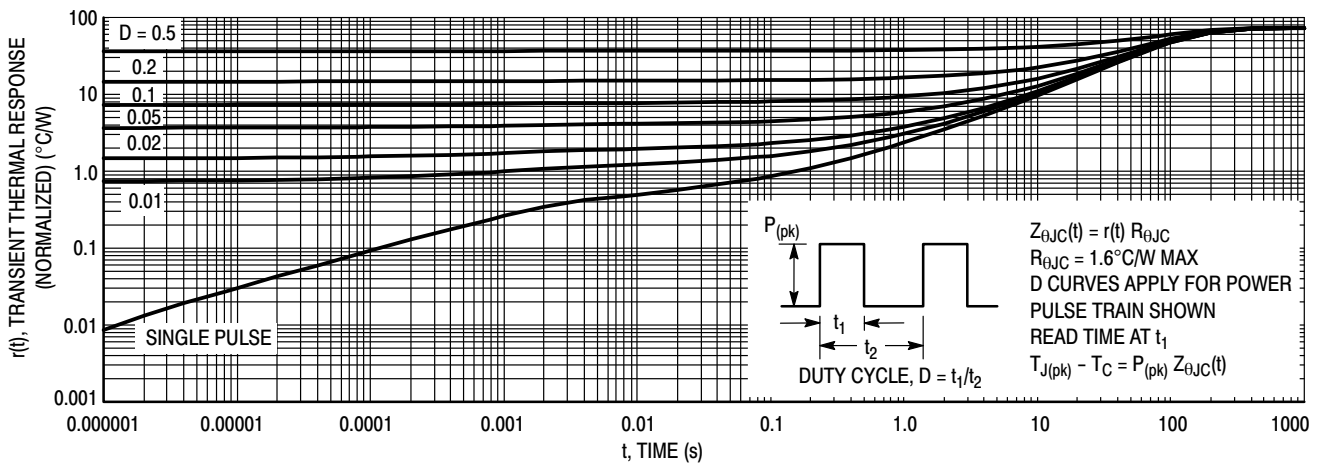
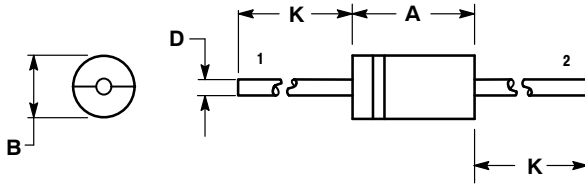


Figure 12. Thermal Response, (MURF550PFG) Junction-to-Ambient ($R_{\theta JA}$)

PACKAGE DIMENSIONS

AXIAL LEAD
CASE 267-05
ISSUE G

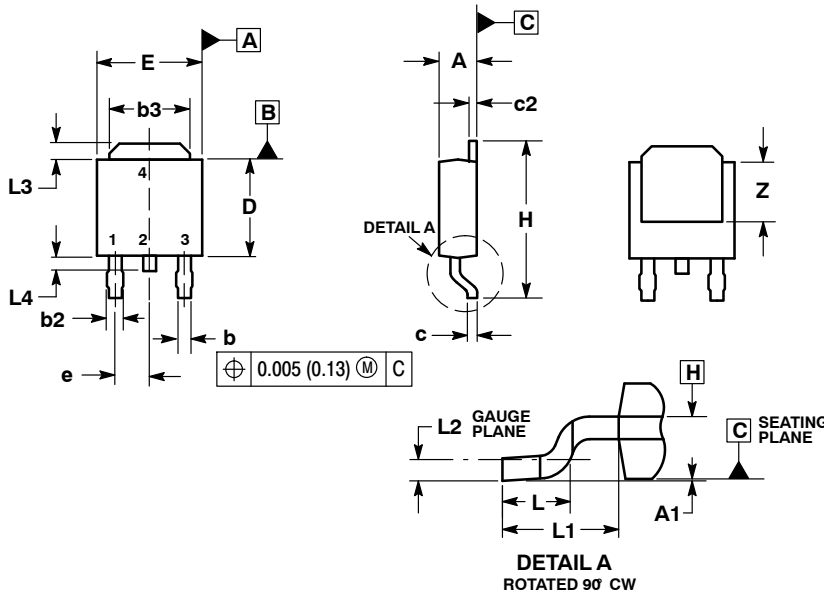


- NOTES:
1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 267-04 OBSOLETE, NEW STANDARD 267-05.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.287	0.374	7.30	9.50
B	0.189	0.209	4.80	5.30
D	0.047	0.051	1.20	1.30
K	1.000	---	25.40	---

STYLE 1:
PIN 1. CATHODE (POLARITY BAND)
2. ANODE

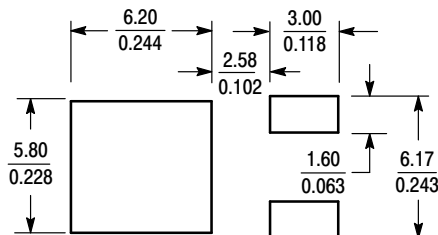
DPAK (SINGLE GAUGE)
CASE 369C-01
ISSUE D



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

SOLDERING FOOTPRINT*



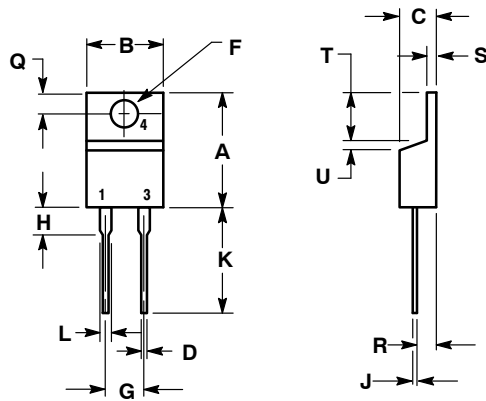
SCALE 3:1 (mm/inches)

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MUR550APFG, MURD550PFG, MUR550PFG, MURF550PFG, NRVUD550PFT4G

PACKAGE DIMENSIONS

TO-220 TWO-LEAD CASE 221B-04 ISSUE E

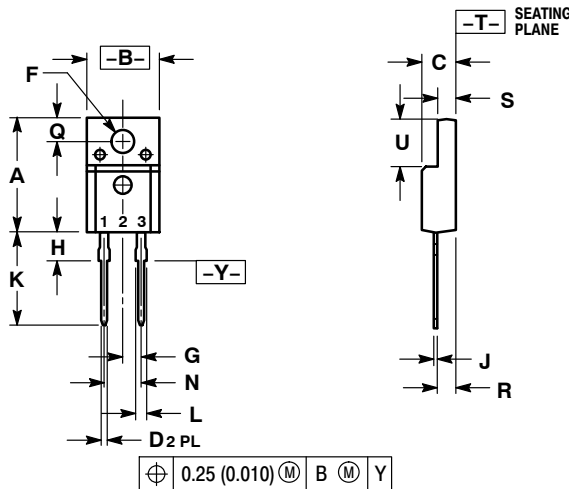


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.620	15.11	15.75
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.82
D	0.025	0.035	0.64	0.89
F	0.142	0.161	3.61	4.09
G	0.190	0.210	4.83	5.33
H	0.110	0.130	2.79	3.30
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.14	1.39
T	0.235	0.255	5.97	6.48
U	0.000	0.050	0.000	1.27

- STYLE 1:
PIN 1. CATHODE
2. N/A
3. ANODE
4. CATHODE

TO-220 FULLPAK, 2-LEAD CASE 221E-01 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.617	0.633	15.67	16.07
B	0.392	0.408	9.96	10.36
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.121	0.129	3.08	3.28
G	0.100 BSC		2.54 BSC	
H	0.117	0.133	2.98	3.38
J	0.018	0.025	0.45	0.64
K	0.499	0.562	12.68	14.27
L	0.045	0.060	1.14	1.52
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.101	0.117	2.56	2.96
S	0.092	0.108	2.34	2.74
U	0.255	0.271	6.48	6.88

- STYLE 1:
PIN 1. CATHODE
2. N/A
3. ANODE

\oplus 0.25 (0.010) M B M Y

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